



2.5A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

Product Summary (@TA = +25°C)

V _{RRM} (V)	I _O (A)	V _F (V)	I _R (μ A)
1000	2.5	1.1	5

Description and Applications

Suitable for AC to DC bridge full wave rectification for SMPS, LED lighting, adapter, battery charger, home appliances, office equipment and telecommunication applications.

Features and Benefits

- Glass Passivated Die Construction
- Compact, Thin Profile Package Design
- Reliable Robust Construction
- Ideal for SMT Manufacturing
- Rated at 1000V PRV
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Mechanical Data

- Case: MSBL
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 (§3)
- Polarity: As marked on Body
- Weight: 0.216 grams (Approximate)







(4) (2)

Internal Schematic

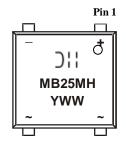
Ordering Information (Note 4)

Part Number	Compliance	Case	Packaging
MSB25MH-13	Commercial	MSBL	2500/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



MB25MH= Product Type Marking Code

Oli = Manufacturers' Code Marking

YWW = Date Code Marking

Y = Last Digit of Year (ex: 6 = 2016)

WW = Week Code (01 to 53)



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristic		Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		1000	V
RMS Reverse Voltage		700	V
Average Rectified Output Current @ T _C = +110°C	Io	2.5	Α
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load		80	Α
Non-Repetitive Peak Forward Surge Current, 1.0ms Single Half Sine-Wave Superimposed on Rated Load		160	Α
I ² t Rating for Fusing (1ms < t < 8.3ms)		26.5	A ² S

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Ambient (Note 5) (Per Element)	$R_{\theta JA}$	35	°C/W
Typical Thermal Resistance, Junction to Case	R ₀ JC	7.8	°C/W
Typical Thermal Resistance, Junction to Lead	$R_{\theta JL}$	16	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	$V_{(BR)R}$	1000	_	_	V	$I_R = 5\mu A$
		_	_	1.02		$I_F = 1.25A, T_A = +25$ °C
Forward Voltage (Per Element)	VF	_	0.78	_	V	$I_F = 1.25A, T_A = +125$ °C
orward voltage (i or Element)	VF	_	_	1.1	•	$I_F = 2.5A, T_A = +25^{\circ}C$
		_	0.86	_		$I_F = 2.5A, T_A = +125$ °C
Leakage Current (Note 6) (Per Element)	I _R	_	0.31	5	I IIA	$V_R = 1000V, T_A = +25$ °C
Leakage Current (Note o) (Fer Element)		_	_	500		$V_R = 1000V, T_A = +125$ °C
Total Capacitance (Note 7)	C _T	_	30	_	pF	$V_R = 4V$, $f = 1.0MHz$

Notes:

- 5. Device mounted on glass-epoxy substrate with 1 oz 20mm x 20mm Cu pad per pin.
- 6. Short duration pulse test used to minimize self-heating effect.
- 7. Measured at 1.0MHz and applied reverse voltage of 4.0V DC.



FIG.1-FORWARD CURRENT DERATING CURVE

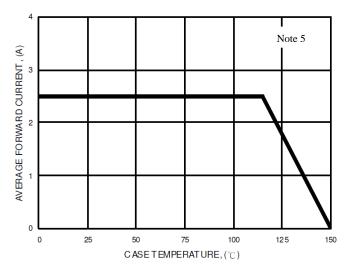


FIG.2- MAXIMUM NON-REPETITIVE SURGE CURRENT

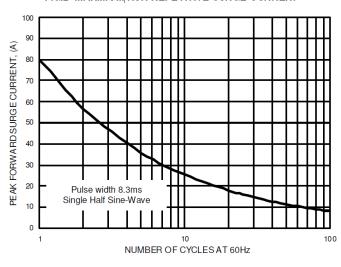


FIG.3 TYPICAL FORWARD CHARACTERISTICS

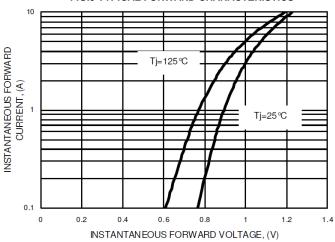


FIG.4- TYPICAL JUNCTION CAPACITANCE

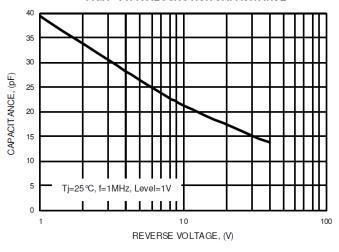
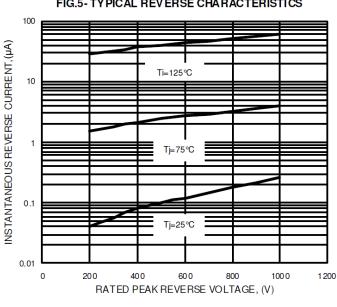
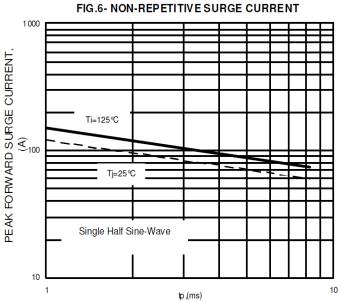


FIG.5-TYPICAL REVERSE CHARACTERISTICS

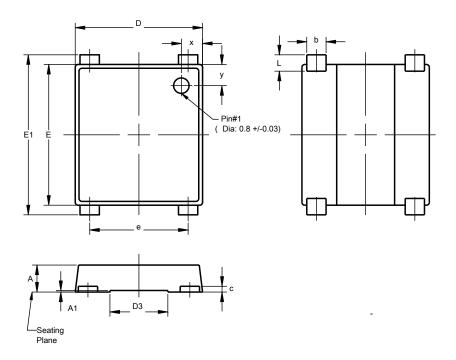






Package Outline Dimensions

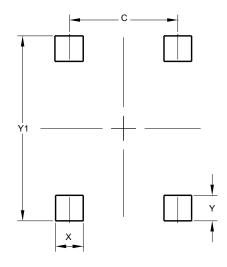
Please see http://www.diodes.com/package-outlines.html for the latest version.



	MSBL				
Dim	Min	Max	Тур		
Α	1.30	1.50	1.40		
A1	0.04	0.08	0.06		
b	0.95	1.15	1.00		
С	0.27	0.40	0.30		
D	6.50	6.70	6.60		
D3	2.90	3.10	3.00		
E	7.20	7.40	7.30		
E1	7.90	8.60	8.30		
е	5.00	5.20	5.10		
L	0.65	1.05	0.85		
X	0.95	1.25	1.10		
У	0.95	1.25	1.10		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)	
С	5.10	
Х	1.30	
Y	1.20	
Y1	8 70	



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